



# 128K BYTE CMOS SECONDARY CACHE MODULE FOR THE INTEL™ i486™

### FEATURES:

- 128KB direct mapped secondary cache module
- Uses the IDT71589 32K x 9 CacheRAM™ with burst counter and self-timed write
- Matches all timing and signals of the i486™ processor
- 72 lead FR-4 SIMM (Single-in-Line Memory Module)
- Single 5V (±5%) power supply
- Multiple GND pins and decoupling capacitors for maximum noise immunity
- Inputs/outputs directly TTL-compatible

### DESCRIPTION:

The IDT7MP6086 is a 128KB direct mapped secondary cache module, using four IDT71589 32K x 9 CacheRAMs in plastic surface mount packages mounted on a multilayer epoxy laminate (FR-4) substrate with gold-plated leads. Extremely high speeds are achieved using IDT's high performance, high reliability CMOS technology. This module is designed to facilitate the implementation of the highest perfor-

mance secondary caches for the i486 architecture while using low-speed logic devices and consuming the minimum board space.

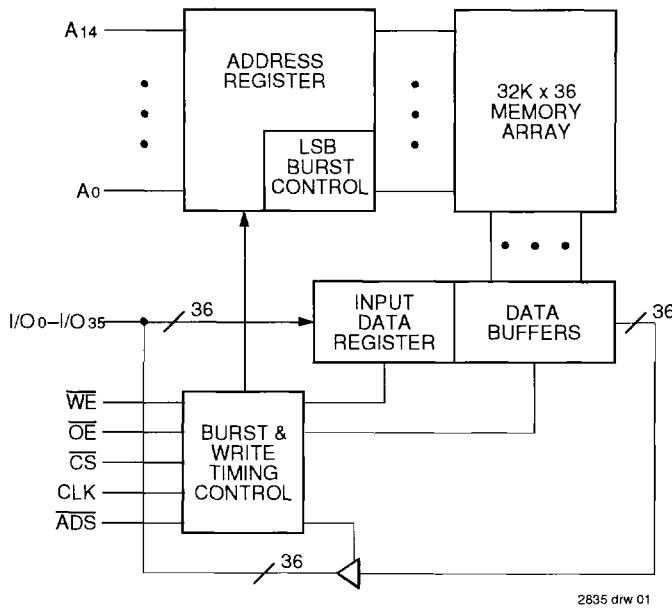
The IDT7MP6086 contains a full set of write data and address registers. These registers are combined with the internal write abort logic to allow the processor to generate a self-timed write based upon a decision which can be left until the end of the write cycle. An internal burst address counter accepts the first cycle address from the processor and then cycles through the adjacent four locations using the i486's burst refill sequence on appropriate rising edges of the system clock.

Three program identification pins are provided so that the system can uniquely identify the IDT7MP6086.

Note that individual parity bits are grouped with their respective bytes, not all at the end.

The SIMM package configuration allows 72 leads to be placed on a package 4.25 inches long, 0.55 inches tall and 0.25 inches thick. All inputs and outputs of the IDT7MP6086 are TTL-compatible and operate from a single 5V power supply.

### FUNCTIONAL BLOCK DIAGRAM



CacheRAM is a trademark and the IDT logo is a registered trademark of Integrated Device Technology, Inc. All others are trademarks of their respective companies.

**PIN CONFIGURATION<sup>(1)</sup>**

GND	2	1	GND
I/O <sub>0</sub>	4	3	V <sub>CC</sub>
I/O <sub>2</sub>	6	5	I/O <sub>1</sub>
I/O <sub>4</sub>	8	7	I/O <sub>3</sub>
I/O <sub>6</sub>	10	9	I/O <sub>5</sub>
I/O <sub>8</sub>	12	11	I/O <sub>7</sub>
$\overline{WE1}$	14	13	$\overline{WE0}$
I/O <sub>10</sub>	16	15	I/O <sub>9</sub>
GND	18	17	I/O <sub>11</sub>
I/O <sub>13</sub>	20	19	I/O <sub>12</sub>
I/O <sub>15</sub>	22	21	I/O <sub>14</sub>
I/O <sub>17</sub>	24	23	I/O <sub>16</sub>
A <sub>1</sub>	26	25	A <sub>0</sub>
A <sub>3</sub>	28	27	A <sub>2</sub>
A <sub>5</sub>	30	29	A <sub>4</sub>
A <sub>7</sub>	32	31	A <sub>6</sub>
$\overline{ADS}$	34	33	A <sub>8</sub>
V <sub>CC</sub>	36	35	CLK
		37	GND
$\overline{CS}$	38	39	$\overline{OE}$
A <sub>9</sub>	40	41	A <sub>10</sub>
A <sub>11</sub>	42	43	A <sub>12</sub>
A <sub>13</sub>	44	45	A <sub>14</sub>
I/O <sub>18</sub>	46	47	I/O <sub>19</sub>
I/O <sub>20</sub>	48	49	I/O <sub>21</sub>
I/O <sub>22</sub>	50	51	I/O <sub>23</sub>
I/O <sub>24</sub>	52	53	I/O <sub>25</sub>
I/O <sub>26</sub>	54	55	GND
$\overline{WE2}$	56	57	$\overline{WE3}$
I/O <sub>27</sub>	58	59	I/O <sub>28</sub>
I/O <sub>29</sub>	60	61	I/O <sub>30</sub>
I/O <sub>31</sub>	62	63	I/O <sub>32</sub>
I/O <sub>33</sub>	64	65	I/O <sub>34</sub>
I/O <sub>35</sub>	66	67	PD <sub>0</sub>
PD <sub>1</sub>	68	69	PD <sub>2</sub>
V <sub>CC</sub>	70	71	GND
GND	72		

SIMM  
TOP VIEW

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**NOTES:**

1. Please consult the factory regarding program identification pins.

**PIN NAMES**

A <sub>0</sub> -A <sub>14</sub>	Address Inputs
I/O <sub>0</sub> -I/O <sub>35</sub>	Data Input/Output
$\overline{CS}$	Chip Select/Count Enable
$\overline{WE0-3}$	Byte Write Enables
$\overline{OE}$	Output Enable
$\overline{ADS}$	Address Status
CLK	System Clock
PD <sub>0-2</sub>	Program Identification
GND	Ground
V <sub>CC</sub>	Power

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**CAPACITANCE** (TA = +25°C, F = 1.0 MHz)

Symbol	Parameter <sup>(1)</sup>	Condition	Max.	Unit
C <sub>IN</sub>	Input Capacitance (Data)	V <sub>IN</sub> = 0V	13	·pF
C <sub>IN</sub>	Input Capacitance (Address & Control)	V <sub>IN</sub> = 0V	42	pF
C <sub>I/O</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	13	pF

**NOTE:**

2835 tbl 02

1. This parameter is guaranteed by design but not tested.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

Symbol	Rating	Value	Unit
V <sub>TERM</sub>	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
T <sub>A</sub>	Operating Temperature	0 to +70	°C
T <sub>BIAS</sub>	Temperature Under Bias	-10 to +85	°C
T <sub>STG</sub>	Storage Temperature	-55 to +125	°C
I <sub>OUT</sub>	DC Output Current	50	mA

**NOTE:**

2835 tbl 03

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE**

Grade	Ambient Temperature	GND	V <sub>CC</sub>
Commercial	0°C to +70°C	0V	5.0V ± 5%

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**RECOMMENDED DC OPERATING CONDITIONS**

Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	4.75	5.0	5.25	V
GND	Supply Voltage	0	0	0.0	V
V <sub>IH</sub>	Input High Voltage	2.2	—	6.0	V
V <sub>IL</sub>	Input Low Voltage	-0.5 <sup>(1)</sup>	—	0.8	V

**NOTE:**

2835 tbl 05

1. V<sub>IL</sub> = -3.0V for pulse width less than 5ns.

**TRUTH TABLE**

CLK	Previous $\overline{ADS}$	$\overline{ADS}$	Address	$\overline{WE}$	$\overline{CS}$	$\overline{OE}$	I/O	Function
↑	H	L	Valid Input	X	X	—	—	Preset Address Counter
↑	X	H	—	—	—	—	—	Ignore External Address Pins
↑	L	X	—	—	—	—	—	Ignore External Address Pins
↑	X	H	—	—	L	—	—	Sequence Address Counter
↑	L	X	—	—	L	—	—	Sequence Address Counter
↑	X	H	—	—	H	—	—	Suspend Address Sequencing
↑	L	X	—	—	H	—	—	Suspend Address Sequencing
—	—	—	—	—	—	H	High-Z	Outputs Disabled
—	—	—	—	H	—	L	DATAOUT	Read
↑	X	H	—	L	L	H	DATAIN	Write
↑	L	X	—	L	L	H	DATAIN	Write
—	—	—	—	L	L	L	—	Not Allowed

**NOTE:**

H = HIGH  
L = LOW  
X = Don't Care  
— = Unrelated  
Hi-Z = High Impedance

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**DC ELECTRICAL CHARACTERISTICS** ( $V_{CC} = 5.0V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $+70^\circ C$ )

Symbol	Parameter	Test Condition	Min.	Max.	Unit
$I_{LI}$	Input Leakage Current (Address & Control)	$V_{CC} = 5.5V$ , $V_{IN} = 0V$ to $V_{CC}$	—	40	$\mu A$
$I_{LI}$	Input Leakage Current (Data)	$V_{CC} = 5.5V$ , $V_{IN} = 0V$ to $V_{CC}$	—	10	$\mu A$
$I_{LO}$	Output Leakage Current	$\overline{CS} = V_{IH}$ , $V_{OUT} = 0V$ to $V_{CC}$ , $V_{CC} = \text{Max.}$	—	10	$\mu A$
$V_{OL}$	Output Low Voltage	$I_{OL} = 8mA$ , $V_{CC} = \text{Min.}$	—	0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -4mA$ , $V_{CC} = \text{Min.}$	2.4	—	V

**DC ELECTRICAL CHARACTERISTICS** ( $V_{CC} = 5.0V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $+70^\circ C$ )

Symbol	Parameter	Test Condition	40MHz	33MHz	Unit
$I_{CC1}$	Operating Power Supply Current	$\overline{CS} = V_{IL}$ Outputs Open $V_{CC} = \text{Max.}$ , $f = 0^{(1)}$	520	520	mA
$I_{CC2}$	Dynamic Operating Current	$\overline{CS} = V_{IL}$ Outputs Open $V_{CC} = \text{Max.}$ , $f = f_{MAX}^{(1)}$	960	880	mA

**NOTE:**

1. At  $f = f_{MAX}$ , address and data inputs are cycling at the maximum frequency of read cycles of  $1/t_{RC}$ .  $f = 0$  means no input lines change.

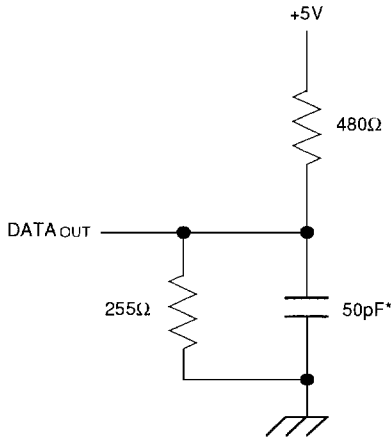
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**AC TEST CONDITIONS**

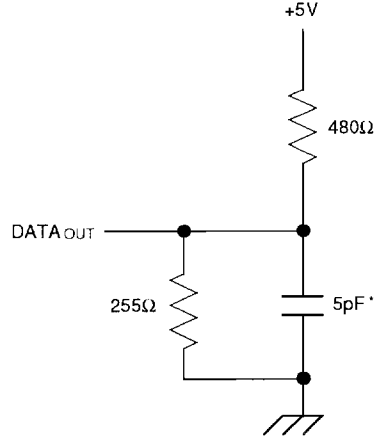
Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1 & 2

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2835 drw 03

Figure 1. Output Load



2835 drw 04

Figure 1. Output Load  
(for tOHZ, tCHZ, tOLZ and tCLZ)

\*including scope and jig

**AC ELECTRICAL CHARACTERISTICS** (VCC = 5.0V ± 5%, TA = 0° to +70°C)

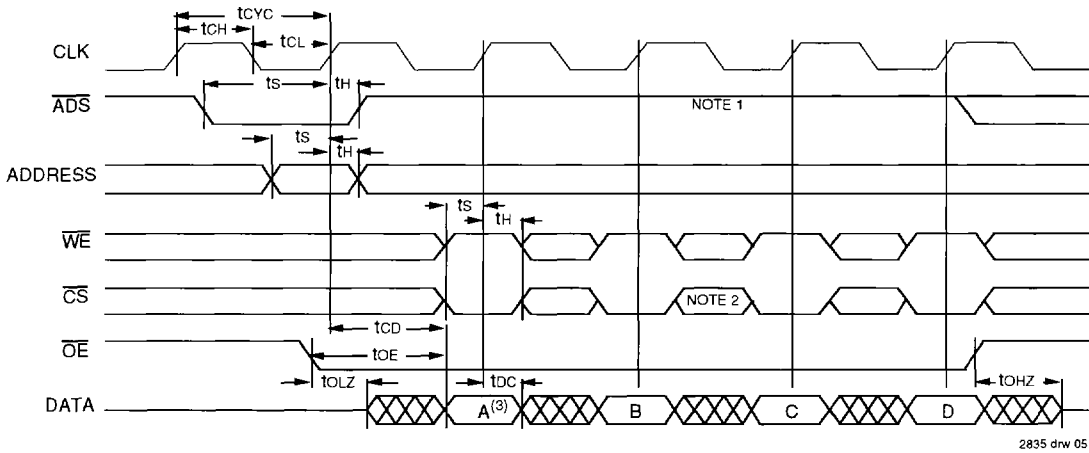
Symbol	Parameter	7MP6086SxxM				Unit
		40 MHz		33 MHz		
		Min.	Max.	Min.	Max.	
tCYC	Clock Cycle Time	25	—	30	—	ns
tCH	Clock Pulse HIGH	10	—	11	—	ns
tCL	Clock Pulse LOW	10	—	11	—	ns
ts1	Set-up Time (ADS, WE, CS)	4	—	4	—	ns
ts2	Set-up Time (Address, Input Data)	5	—	5	—	ns
th1	Hold Time (CS↓ Input Data)	1	—	1	—	ns
th2	Hold Time (CS↑, WE, Address)	2	—	2	—	ns
tADSH	Hold Time (ADS)	3	—	3	—	ns
tCD	Clock to Data Valid	—	19	—	24	ns
tDC	Data Valid After Clock	4	—	4	—	ns
tOE	Output Enable to Output Valid	—	8	—	9	ns
tOLZ	Output Enable to Output in Low-Z <sup>(1,2)</sup>	2	—	2	—	ns
tOHZ	Output Disable to Output in High-Z <sup>(1,2)</sup>	—	8	—	9	ns

**NOTES:**

1. Transition is measured ±200mV from low or high-impedance voltage with load (Figure 2).
2. This parameter is guaranteed, but not tested.

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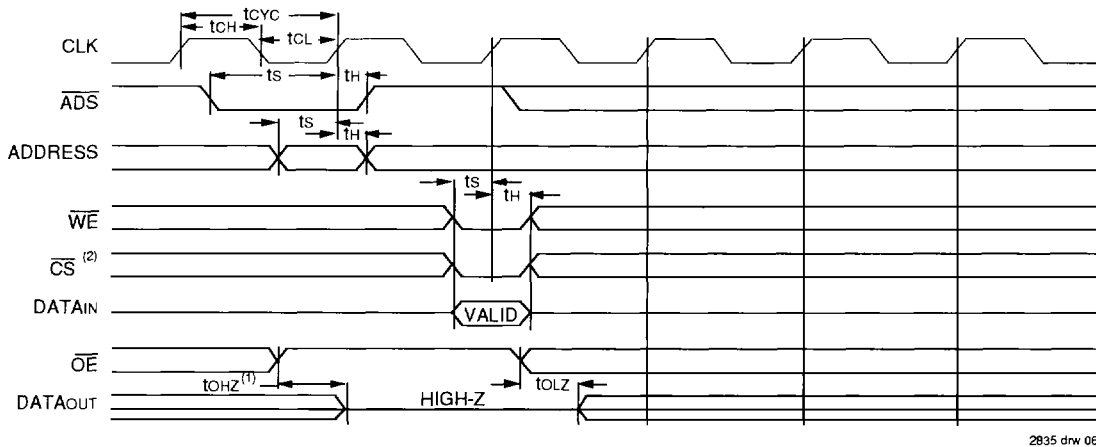
### TIMING WAVEFORM OF BURST READ CYCLE



**NOTES:**

1. If  $\overline{ADS}$  goes LOW during a burst cycle, a new address will be loaded and another burst cycle will be started.
2. If  $\overline{CS}$  is taken inactive during a burst read cycle, the burst counter will discontinue counting until  $\overline{CS}$  input again goes active. The timing of the  $\overline{CS}$  input for this control of the burst counter must satisfy setup and hold parameters  $t_s$  and  $t_h$ .
3. A-Data from input address. B-Data from input address except  $A_0$  is now  $\overline{A}_0$ . C-Data from input address except  $A_1$  is now  $\overline{A}_1$ . D-Data from input address except  $A_0$  and  $A_1$  are now  $\overline{A}_0$  and  $\overline{A}_1$ .

### TIMING WAVEFORM OF WRITE CYCLE

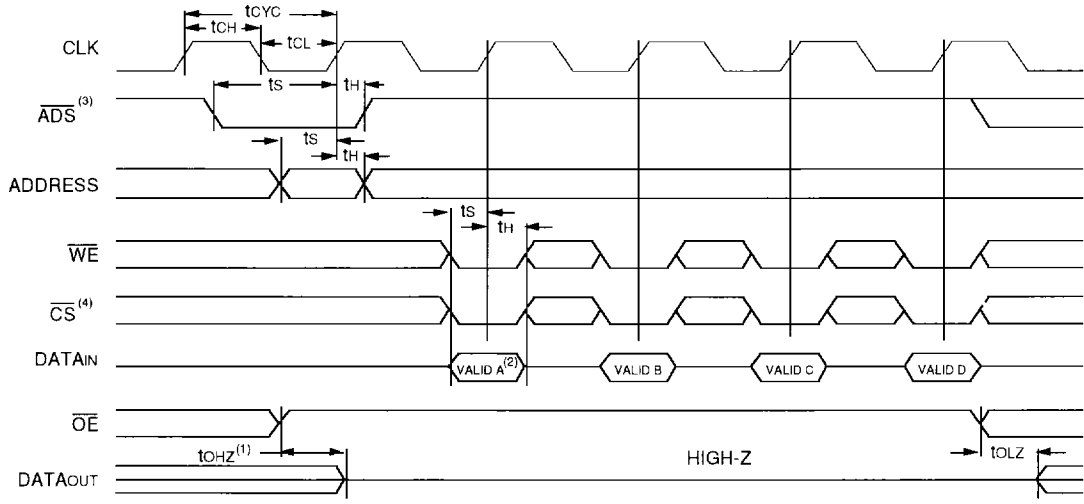


**NOTES:**

1.  $\overline{OE}$  Must be taken inactive at least as long as  $t_{OHZ} + t_s$  before the second rising clock edge of write cycle.
2.  $\overline{CS}$  timing is the same as any synchronous signal when used to block writes or to stop the burst count sequence.

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### TIMING WAVEFORM OF BURST WRITE CYCLE

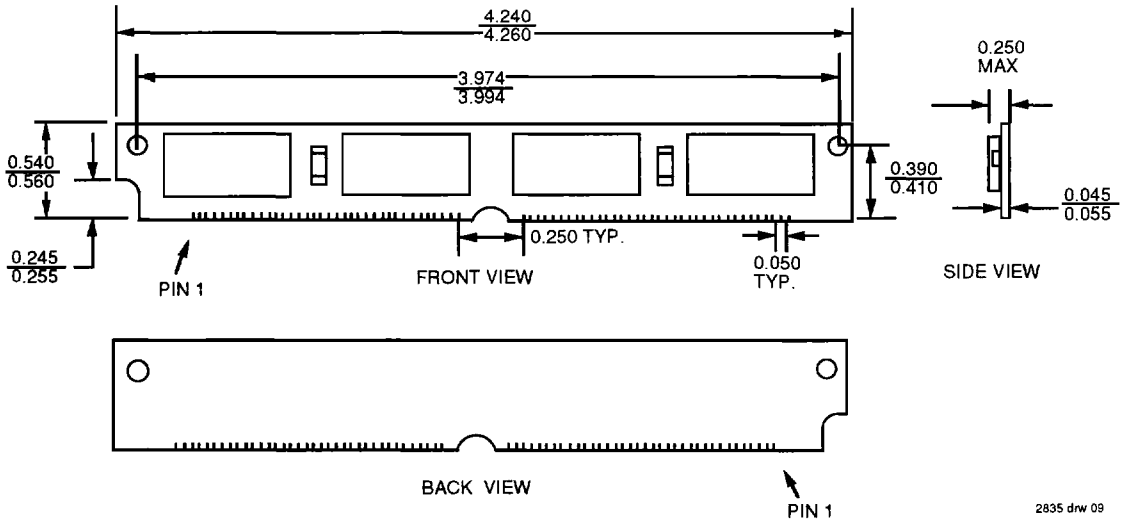


2835 drw 07

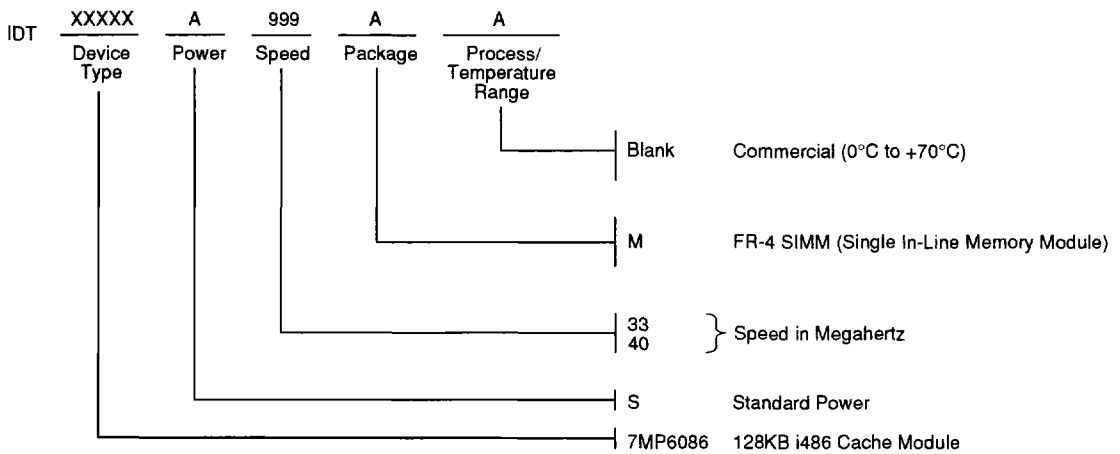
**NOTES:**

1.  $\overline{OE}$  Must be taken inactive at least as long as  $t_{OHZ} + t_s$  before the second rising clock edge of write cycle.
2. A-Data to be written to original input address.  
 B-Data to be written to original input address except  $A_0$  is now  $\overline{A}_0$ .  
 C-Data to be written to original input address except  $A_1$  is now  $\overline{A}_1$ .  
 D-Data to be written to original input address except  $A_0$  and  $A_1$  are now  $\overline{A}_0$  and  $\overline{A}_1$ .
3. If  $\overline{ADS}$  goes low during a burst cycle, a new address will be loaded, and another burst cycle will be started.
4. If  $\overline{CS}$  is taken inactive during a burst write cycle the burst counter will discontinue counting until the  $\overline{CS}$  input again goes active. The timing of the  $\overline{CS}$  input for this control of the burst counter must satisfy setup and hold parameters  $t_s$  and  $t_h$ .  $\overline{CS}$  timing is the same as any synchronous signal when used to block writes or to stop the burst count sequence.

**PACKAGE DIMENSIONS**



**ORDERING INFORMATION**



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